

### ✓ Active - 165mW Worst Case ✓ Standby - 1.7mW Worst Case (CMOS-input levels)

MARKING -15 -17 -20 -25 -30 J No. 110

• Operating Temperature Ranges Military (-55°C to +125°C) M

Ceramic DIP (600mils)

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## GENERAL DESCRIPTION

The SMJ27C256 series is a set of 262,144 bit, ultravioletlight erasable, electrically programmable read-only memories. These devices are fabricated using power-saving CMOS technology for high speed and simple interface with MOS and bipolar circuits. All inputs (including program data inputs) can be driven by Series 54 TTL circuits without the use of external pullup resistors. Each output can drive one Series 54 TTL circuit without external resistors. The data outputs are 3-state for connecting multiple devices to a common bus. The SMJ27C256 is pin-compatible with 28-pin 256K ROMs and EPROMs. It is offered in a 600mil dual-in-line ceramic pagackage (J suffix) rated for operation from -55°C to 125°C.

Because this EPROM operates from a single 5V supply (in the read mode), it is ideal for use in microprocessor-based systems. One other supply (13V) is needed for programming. All programming signals are TTL level. This device is programmable by the SNAP! Pulse programming algorithm. The SNAP! Pulse programming algorithm uses a  $V_{PP}$  of 13V and a  $V_{CC}$  of 6.5V for a nominal programming time of four seconds. For programming outside the system, existing EPROM programmers can be used. Locations can be programmed singly, in blocks, or at random.

**OPTIONS** 

150ns access

170ns access

200ns access

250ns access

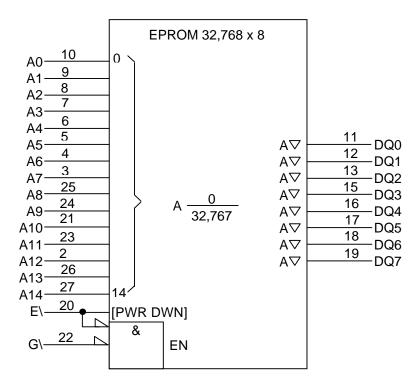
300ns access

Package(s)

• Timing



## FUNCTIONAL BLOCK DIAGRAM\*



\* This symbol is in accordance with ANSI/IEEE std 91-1984 and IEC Publication 617-12.

## OPERATION

The seven modes of operation for the SMJ27C256 are listed in Table 1. The read mode requires a single 5V supply. All inputs are TTL level except for  $V_{pp}$  during programming (13V for SNAP! Pulse), and (12V) on A9 for signature mode.

FUNCTION				MODE*	r			
(PINS)	READ	OUTPUT DISABLE	STANDBY	PROGRAMMING	VERIFY	PROGRAM INHIBIT	SIGNATU	RE MODE
E\ (20)	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IL</sub>	V <sub>IH</sub>	V <sub>IH</sub>	V	, IL
G\ (22)	V <sub>IL</sub>	V <sub>IH</sub>	Х	V <sub>IH</sub>	V <sub>IL</sub>	Х	V	, IL
V <sub>PP</sub> (1)	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>PP</sub>	V <sub>PP</sub>	V <sub>PP</sub>	V <sub>CC</sub>	
V <sub>CC</sub> (28)	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	V <sub>CC</sub>	
A9 (24)	Х	Х	Х	Х	Х	Х	V <sub>ID</sub>	V <sub>ID</sub>
A0 (10)	Х	Х	Х	Х	Х	Х	V <sub>IL</sub>	V <sub>IH</sub>
DQ0-DQ7							CODE	
(11-13, 15-19)	Data Out	High-Z	High-Z	Data In	Data Out	High-Z	MFG	DEVICE
(11-13, 15-19)							97	04

## **TABLE 1. OPERATION MODES**

\* X can be  $V_{IL}$  or  $V_{IH}$ .



# UVEPROM SMJ27C256

## **READ/OUTPUT DISABLE**

When the outputs of two or more SMJ27C256s are connected in parallel on the same bus, the output of any particular device in the circuit can be read with no interference from the competing outputs of the other devices. To read the output of the selected SMJ27C256, a low-level signal is applied to  $E \setminus$ and  $G \setminus$ . All other devices in the circuit should have their outputs disabled by applying a high-level signal to one of these pins. Output data is accessed at pins DQ0 through DQ7.

## LATCHUPIMMUNITY

Latchup immunity on the SMJ27C256 is a minimum of 250mA on all inputs and outputs. This feature provides latchup immunity beyond any potential transients at the printed circuit board level when the EPROM is interfaced to industry standard TTL or MOS logic devices. Input/output layout approach controls latchup without compromising performance or packing density.

## **POWER DOWN**

Active  $I_{CC}$  supply current can be reduced from 25mA (SMJ27C256-15 through SMJ27C256-25) to 500µA (TTL-level inputs) or 300µA (CMOS-level inputs) by applying a high TTL/CMOS signal to the E\ pin. In this mode all outputs are in the high-impedance state.

## ERASURE

Before programming, the SMJ27C256 is erased by exposing the chip through the transparent lid to a high-intensity ultraviolet light (wavelength 2537 Å). EPROM erasure before programming is necessary to ensure that all bits are in the logic-high state. Logic-lows are programmed into the desired locations. A programmed logic-low can be erased only by ultraviolet light. The recommended minimum exposure dose (UV intensity x exposure time) is  $15W \cdot s/cm^2$ . A typical  $12mW/cm^2$ , filterless UV lamp erases the device in 21 minutes. The lamp should be located about 2.5cm above the chip during erasure. After erasure, all bits are in the high state. It should be noted that normal ambient light contains the correct wavelength for erasure; therefore, when using the SMJ27C256, the window should be covered with an opaque label.

## SNAP! PULSE PROGRAMMING

The SMJ27C256 EPROM is programmed by using the SNAP! Pulse programming algorithm as illustrated by the flowchart in Figure 1. This algorithm programs the device in a nominal time of 4 seconds. Actual programming time varies as a function of the programmer used.

Data is presented in parallel (eight bits) on pins DQ0 to DQ7. Once addresses and data are stable,  $E \setminus is$  pulsed.

The SNAP! Pulse programming algorithm uses initial pulses of 100 microseconds ( $\mu$ s) followed by a byte-verification step to determine when the addressed byte has been successfully programmed. Up to ten 100 $\mu$ s pulses per byte are provided before a failure is recognized.

The programming mode is achieved when  $V_{pp} = 13V$ ,  $V_{CC} = 6.5V$ ,  $G \setminus = V_{IH}$ , and  $E \setminus = V_{IL}$ . More than one device can be programmed when the devices are connected in parallel. Locations can be programmed in any order. When the SNAP! Pulse programming routine is completed, all bits are verified with  $V_{CC} = V_{pp} = 5V$ .

## **PROGRAM INHIBIT**

Programming can be inhibited by maintaining a high-level input on  $E \setminus .$ 

## PROGRAM VERIFY

Programmed bits can be verified with  $V_{pp}=13V$  when  $G \backslash = V_{_{II}}$  , and  $E \backslash = V_{_{IH}}.$ 

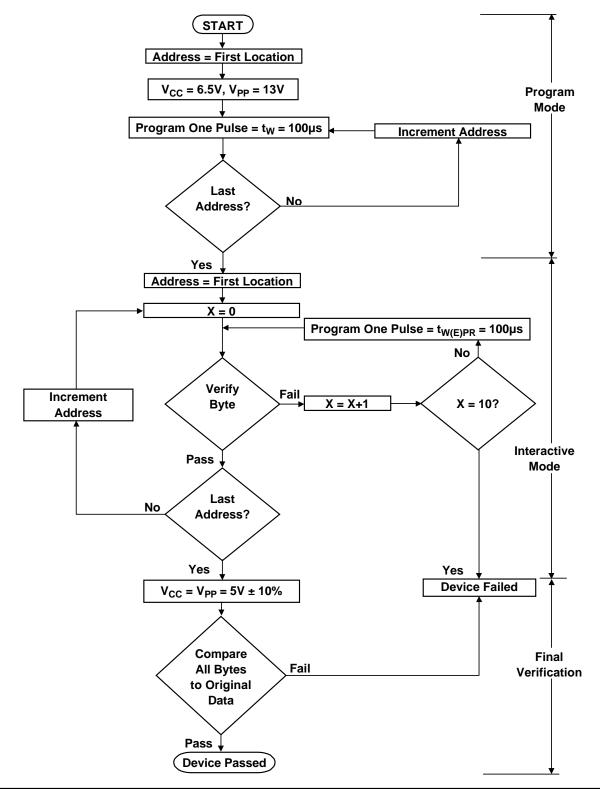
## SIGNATURE MODE

The signature mode provides access to a binary code identifying the manufacturer and device type. This mode is activated when A9 is forced to  $12V \pm 0.5V$ . Two identifier bytes are accessed by A0 (terminal 10); i.e.,  $A0=V_{IL}$  accesses the manufacturer code, which is output on DQ0-DQ7;  $A0=V_{IH}$  accesses the device code, which is also output on DQ0-DQ7. All other addresses must be held at VIL. Each byte contains odd parity on bit DQ7. The manufacturer code for these devices is 97h and the device code is 04h.

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# UVEPROM SMJ27C256

#### ABSOLUTE MAXIMUM RATINGS\*

Supply Voltage Range, V <sub>CC</sub> **0.6V to +7.0V
Supply Voltage Range, V <sub>pp</sub> **0.6V to +14.0V
Input Voltage Range, All inputs except A9**0.6V to +6.5V
A90.6V to +13.5V
Output Voltage Range**0.6V to $V_{CC}$ +1V
Minimum Operating Free-air Temperature, T <sub>A</sub> 55°C
Winning Free an Temperature, T <sub>A</sub>
Maximum Operating Case Temperature, $T_{c}$

\*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

\*\* All voltage values are with respect to GND.

## **RECOMMENDED OPERATING CONDITIONS**

				MIN	TYP	MAX	UNIT
V <sub>CC</sub>	Supply Voltage	Read Mode <sup>1</sup>		4.5	5	5.5	V
v CC	Cupply voltage	SNAP! Pulse programming a	algorithm	6.25	6.5	6.75	V
V <sub>PP</sub>	Supply Voltage	Read Mode <sup>2</sup>				V <sub>CC</sub> -0.6	V
• PP	Cupply Voltage	SNAP! Pulse programming a	algorithm	12.75	13	13.25	V
V	High-level input voltage		TTL inputs	2		V <sub>CC</sub> +1	V
V <sub>IH</sub>			CMOS inputs	V <sub>CC</sub> -0.2		V <sub>CC</sub> +1	V
V.	Low-level input v	oltago	TTL inputs	-0.5		0.8	V
V <sub>IL</sub>		ollage	CMOS inputs	-0.5		0.2	V
V <sub>ID</sub>	Voltage level on	/oltage level on A9 for signature mode		11.5		13	V
T <sub>A</sub>	Operating free-ai	emperature		-55			°C
Т <sub>С</sub>	Operating case te	mperature				+125	°C

NOTES:

1.  $V_{CC}$  must be applied before or at the same time as  $V_{pp}$  and removed after or at the same time as  $V_{pp}$ . The deivce must not be inserted into or removed from the board when  $V_{pp}$  or  $V_{CC}$  is applied.

2.  $V_{PP}$  can be connected to  $V_{CC}$  directly (except in the program mode).  $V_{CC}$  supply current in this case would be  $I_{CC2} + I_{PP1}$ .

# ELECTRICAL CHARACTERISTICS OVER RECOMMENDED RANGES OF SUPPLY VOLTAGE AND OPERATING FREE-AIR TEMPERATURE

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>1</sup>	MAX	UNIT	
V <sub>OH</sub>	High-level output voltage		Ι <sub>ΟΗ</sub> = -400μΑ	2.4			V
V <sub>OL</sub>	Low-level output voltage		I <sub>OL</sub> = 2.1mA			0.4	V
I <sub>I</sub>	Input current (leakage)		V <sub>I</sub> = 0V to 5.5V			±1	μA
Ι <sub>Ο</sub>	Output current (leakage)		$V_{O} = 0V$ to $V_{CC}$			±1	μA
I <sub>PP1</sub>	V <sub>PP</sub> supply current		$V_{PP} = V_{CC} = 5.5V$			10	μA
I <sub>PP2</sub>	V <sub>PP</sub> supply current (during program pulse) <sup>2</sup>		V <sub>PP</sub> = 13V		35	50	mA
I	\/	TTL-Input Level	V <sub>CC</sub> = 5.5V, E\=V <sub>IH</sub>			500	μA
I <sub>CC1</sub>	V <sub>CC</sub> supply current (standby)	CMOS-Input Level	$V_{CC} = 5.5V, E = V_{CC}$			300	μA
I <sub>CC2</sub>	V <sub>CC</sub> supply current (active)	'27C256-15 '27C256-17 '27C256-20 '27C256-25	E\=V <sub>IL</sub> , V <sub>CC</sub> =5.5V t <sub>cycle</sub> = minimum, outputs open		15	25	mA
I <sub>OS</sub>	Output current (leakage)	-				100	mA

#### NOTES:

1. Typical values are at  $T_A = 25^{\circ}C$  and nominal voltages.

2. This parameter has been characterized at 25°C and is not tested.



# CAPACITANCE OVER RECOMMENDED RANGES OF SUPPLY VOLTAGE AND OPERATING FREE-AIR TEMPERATURE, f = 1MHz\*

PARAMETER		<b>TEST CONDITIONS</b>	TYP**	MAX	UNIT	
Ci	Input capacitance	$V_I = 0V$	6	10	pF	
Co	Output capacitance	$V_{O} = 0V$	10	14	pF	

\* Capacitance measurements are made on a sample basis only.

\*\* Typical values are at  $T_A = 25^{\circ}C$  and nominal voltages.

# SWITCHING CHARACTERISTICS OVER RECOMMENDED RANGES OF SUPPLY VOLTAGE AND OPERATING FREE-AIR TEMPERATURE<sup>1,2</sup>

	PARAMETER	TEST	-15		-17		UNIT
	PARAMETER		MIN	MAX	MIN	MAX	
t <sub>a(A)</sub>	Access time from address			150		170	ns
t <sub>a(E)</sub>	Access time from E\			150		170	ns
t <sub>en(G)R</sub>	Output enable time from G\			70		70	ns
t <sub>dis</sub>	Disable time of output from G\ or E whichever occurs first <sup>3</sup>	see Figure 2	0	55	0	55	ns
t <sub>v(A)</sub>	Output data valid time after change of address, E or G whichever occurs first <sup>3</sup>		0		0		ns

	PARAMETER		-20		-25		-30		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
t <sub>a(A)</sub>	Access time from address			200		250		300	ns	
t <sub>a(E)</sub>	Access time from E\			200		250		300	ns	
t <sub>en(G)R</sub>	Output enable time from G\			75		100		120	ns	
t <sub>dis</sub>	Disable time of output from G\ or E whichever occurs first <sup>3</sup>	see Figure 2	0	60	0	60	0	105	ns	
t <sub>v(A)</sub>	Output data valid time after change of address, E or G whichever occurs first <sup>3</sup>		0		0		0		ns	

NOTES:

1. Timing measurements are made at 2V for logic high and 0.8V for logic low (see figure 2).

2. Common test conditions apply for  ${\rm t}_{\rm dis}$  except during programming.

3. Value calculated from 0.5V delta to measured output level. This parameter is only sampled and not 100% tested.

# SWITCHING CHARACTERISTICS FOR PROGRAMMING: $V_{cc} = 6.5V$ and $V_{pp} = 13V$ (SNAP! Pulse), $T_{a} = 25^{\circ}C$

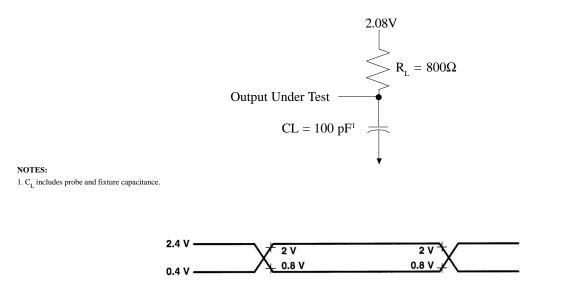
	PARAMETER	MIN	MAX	UNIT
t <sub>dis(G)</sub>	Output disable time from G\	0	130	ns
t <sub>en(G)W</sub>	Output enable time from G\		150	ns

# UVEPROM SMJ27C256

# RECOMMENDED TIMING REQUIREMENTS FOR PROGRAMMING: $V_{CC} = 6.5$ and $V_{PP} = 13$ (SNAP! Pulse), $T_A = 25^{\circ}C$ (See Figure 2)

		MIN	TYP	MAX	UNIT
t <sub>h(A)</sub>	Hold Time, Address	0			μs
t <sub>h(D)</sub>	Hold Time, Data	2			μs
t <sub>w(E)PR</sub>	Pulse Duration, Initial Program	95	100	105	μs
t <sub>su(A)</sub>	Setup Time, Address	2			μs
t <sub>su(G)</sub>	Setup Time, G\	2			μs
t <sub>su(E)</sub>	Setup Time, E\	2			μs
t <sub>su(D)</sub>	Setup Time, Data	2			μs
t <sub>su(VPP)</sub>	Setup Time, V <sub>PP</sub>	2			μs
t <sub>su(VCC)</sub>	Setup Time, V <sub>CC</sub>	2			μs

## PARAMETER MEASUREMENT INFORMATION

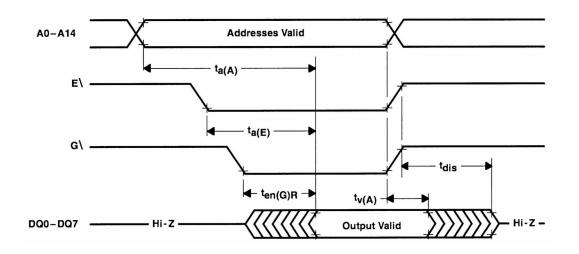


The AC testing inputs are driven at 2.4V for logic high and 0.4V for logic low. Timing measurements are made at 2V for logic high and 0.8V for logic low for both inputs and outputs.

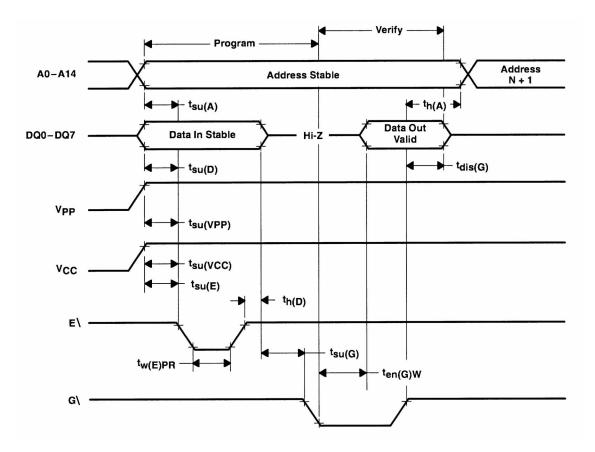
## FIGURE 2. LOAD CIRCUIT AND VOLTAGE WAVEFORMS



## FIGURE 3. READ-CYCLE TIMING



## FIGURE 4. PROGRAM-CYCLE TIMING (SNAP! PULSE PROGRAMMING)



**UVEPROM** 

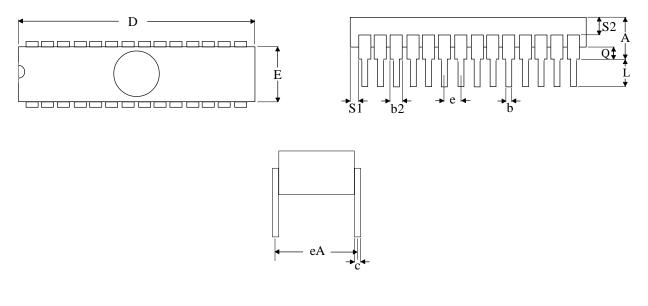
SMJ27C256

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## **MECHANICAL DEFINITION\***

ASI Case #110 (Package Designator CW) SMD 5962-86063, Case Outline X



	SMD SPEC	FICATIONS
SYMBOL	MIN	MAX
A		0.232
b	0.014	0.026
b2	0.045	0.065
С	0.008	0.018
D		1.490
E	0.500	0.610
eA	0.600	BSC
е	0.100	BSC
L	0.125	0.200
Q	0.015	0.060
S1	0.005	
S2	0.005	

**NOTE:** These dimensions are per the SMD. ASI's package dimensional limits may differ, but they will be within the SMD limits.



## **ORDERING INFORMATION**

EXAMPLE: SMJ27C256-30JM

Device Number	Speed ns	Package Type	Operating Temp.
SMJ27C256	-15	J	*
SMJ27C256	-17	J	*
SMJ27C256	-20	J	*
SMJ27C256	-25	J	*
SMJ27C256	-30	J	*

## \*AVAILABLE PROCESSES

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M = Extended Temperature Range

-55°C to +125°C



# ASI TO DSCC PART NUMBER CROSS REFERENCE\*

## **ASI Package Designator J**

TI Part #**
SMJ27C256-15JM
SMJ27C256-17JM
SMJ27C256-20JM
SMJ27C256-25JM
SMJ27C256-30JM

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### SMD Part #

5962-8606305XA 5962-8606304XA 5962-8606301XA 5962-8606302XA 5962-8606303XA

\* ASI part number is for reference only. Orders received referencing the SMD part number will be processed per the SMD. \*\* Parts are listed on SMD under the old Texas Instruments part number. ASI purchased this product line in November of 1999.